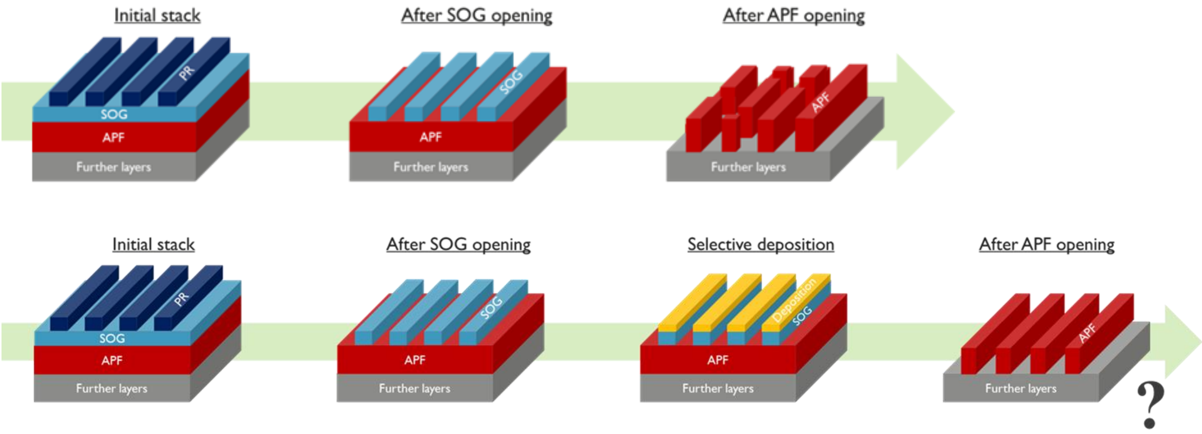
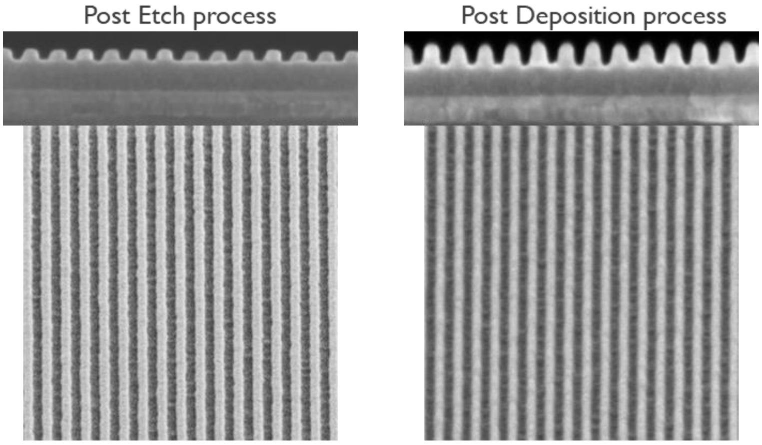


Figure 1 – Standard flow result in non-continue aC lines. An approach using a PECVD process in order to add a selective layer on top of SoG prior aC transfer is introduced to reduce the defectivity (especially the number of breaks).


Post Etch process

Post Deposition process

Figure 2 - Cross/tilted SEM views a) post etch SoG opening + PR strip and b) post selective PECVD on top of SoG.

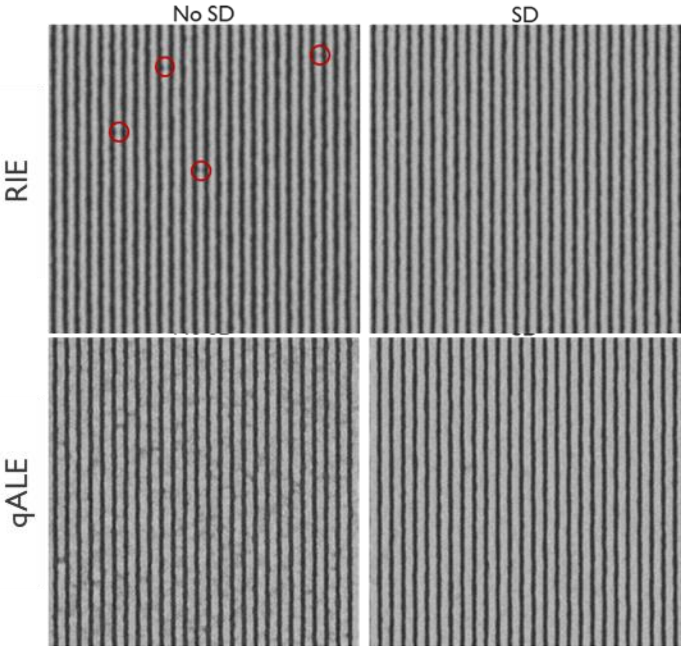


Figure 3 - CDSEM inspections post APF opening (qALE) w/wo SD at wafer center for P32 CAR.